

Abstract

ADHESIVE TAPE FOR SEMICONDUCTOR PROCESSING, AND SEMICONDUCTOR DEVICE MANUFACTURING METHOD

The pressure sensitive adhesive tape for semiconductor processing according to the present invention comprises a base which has a Young's modulus of 1000 MPa or more at 23°C, a buffer layer which is provided on at least one surface of this base, and a pressure sensitive adhesive layer provided on the other surface of the base, wherein the buffer layer has a tensile storage elastic modulus (E_{23}) of 100-2000 MPa at 23°C, and a tensile storage elastic modulus (E_{60}) of 20-1000 MPa at 60°C.

(No Fig.)